

Title (en)
METHOD FOR BONDING CHIPS TO A SUBSTRATE BY DIRECT BONDING

Title (de)
VERFAHREN ZUM BONDEN VON CHIPS MIT EINEM SUBSTRAT DURCH DIREKTES BONDEN

Title (fr)
PROCÉDÉ DE COLLAGE DE PUCES À UN SUBSTRAT PAR COLLAGE DIRECT

Publication
EP 4078663 A1 20221026 (FR)

Application
EP 20823879 A 20201217

Priority
• FR 1914956 A 20191219
• EP 2020086664 W 20201217

Abstract (en)
[origin: CA3161399A1] The method for bonding chips (100) to a substrate (101) by direct bonding comprises a step of providing a medium (105) where the chips (100) are in contact, the chips (100) which contact with the medium (105) being customised. Said bonding method comprises: - a step of forming a liquid film (103) on one face (104) of the substrate (101), - a step of bringing the chips (100) into contact with the liquid film (103), the contact between the chips (100) and the liquid film (103) causing the chips (100) to be attracted to the substrate (101), - a step of evaporating the liquid film (103) to bond the chips (100) to the substrate (101) by direct bonding.

IPC 8 full level
H01L 21/60 (2006.01)

CPC (source: EP US)
H01L 21/6835 (2013.01 - EP); **H01L 21/6836** (2013.01 - EP); **H01L 24/08** (2013.01 - US); **H01L 24/74** (2013.01 - US); **H01L 24/80** (2013.01 - US); **H01L 24/95** (2013.01 - EP); **H01L 25/0655** (2013.01 - US); **H01L 25/50** (2013.01 - EP); **H01L 24/74** (2013.01 - EP); **H01L 24/80** (2013.01 - EP); **H01L 24/97** (2013.01 - EP); **H01L 2221/68309** (2013.01 - EP); **H01L 2221/68313** (2013.01 - EP); **H01L 2221/68354** (2013.01 - EP); **H01L 2221/68386** (2013.01 - EP); **H01L 2224/08221** (2013.01 - US); **H01L 2224/75317** (2013.01 - EP); **H01L 2224/7565** (2013.01 - EP); **H01L 2224/75824** (2013.01 - EP); **H01L 2224/7598** (2013.01 - EP); **H01L 2224/80004** (2013.01 - EP US); **H01L 2224/80011** (2013.01 - EP); **H01L 2224/80013** (2013.01 - EP); **H01L 2224/80085** (2013.01 - US); **H01L 2224/80136** (2013.01 - EP); **H01L 2224/80143** (2013.01 - EP); **H01L 2224/80395** (2013.01 - US); **H01L 2224/80894** (2013.01 - EP); **H01L 2224/94** (2013.01 - EP); **H01L 2224/95001** (2013.01 - EP); **H01L 2224/95136** (2013.01 - EP); **H01L 2224/95146** (2013.01 - EP); **H01L 2224/97** (2013.01 - EP)

Citation (search report)
See references of WO 2021122909A1

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